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(54) Title: ROUGHENED CARRIER FOR DEBONDING OF BONDED STACK

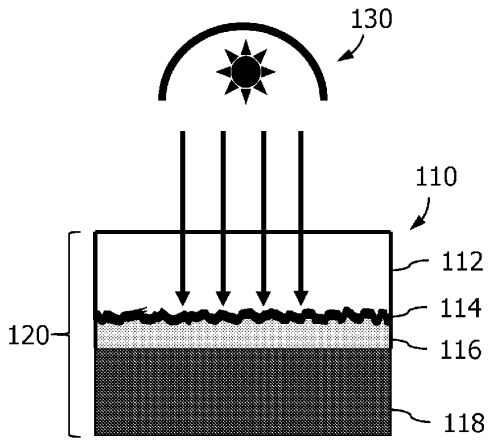


FIG. 7B

(57) Abstract: Temporary electronics carrier structures and associated systems and methods. A carrier structure for temporarily carrying an electronics structure to be debonded from the carrier structure. The carrier structure includes a roughened surface that has an average surface roughness between about 50nm and about 5 microns. A temporarily bonded stack includes the carrier structure, an electronics structure, and a temporary adhesive located between the carrier structure and the electronics structure. A system for debonding the temporarily bonded stack includes a light source configured to emit light into the carrier structure toward a roughened face thereof.

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